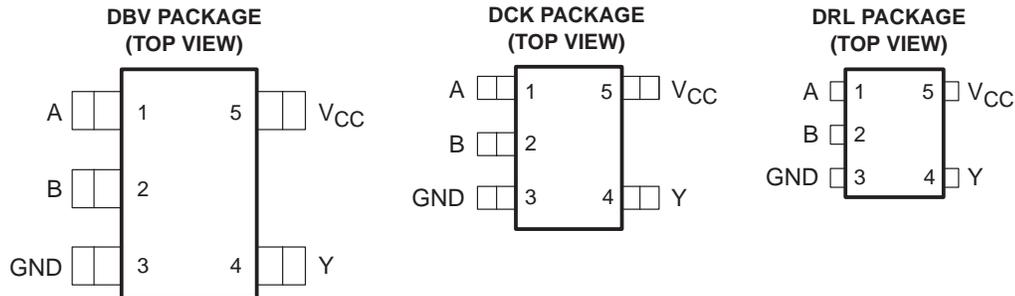


# SN74AHC1G86 SINGLE 2-INPUT EXCLUSIVE-OR GATE

SCLS323M – MARCH 1996 – REVISED JUNE 2005

- Operating Range of 2 V to 5.5 V
- Max  $t_{pd}$  of 8 ns at 5 V
- Low Power Consumption, 10- $\mu$ A Max  $I_{CC}$
- $\pm 8$ -mA Output Drive at 5 V
- Schmitt Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

## description/ordering information

The SN74AHC1G86 is a single 2-input exclusive-OR gate. The device performs the Boolean function  $Y = A \oplus B$  or  $Y = \bar{A}B + A\bar{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
–40°C to 85°C	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G86DBVR	A86_
		Reel of 250	SN74AHC1G86DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74AHC1G86DCKR	AH_
		Reel of 250	SN74AHC1G86DCKT	
	SOT (SOT-553) – DRL	Reel of 4000	SN74AHC1G86DRLR	AH_

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

‡ The actual top-side marking has one additional character that designates the assembly/test site.

## FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L



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# SN74AHC1G86 SINGLE 2-INPUT EXCLUSIVE-OR GATE

SCLS323M – MARCH 1996 – REVISED JUNE 2005

## recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	V
		V <sub>CC</sub> = 3 V	2.1	
		V <sub>CC</sub> = 5.5 V	3.85	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5	V
		V <sub>CC</sub> = 3 V	0.9	
		V <sub>CC</sub> = 5.5 V	1.65	
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V	-50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	-4	
		V <sub>CC</sub> = 5 V ± 0.5 V	-8	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V	50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	4	
		V <sub>CC</sub> = 5 V ± 0.5 V	8	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V	100	ns/V
		V <sub>CC</sub> = 5 V ± 0.5 V	20	
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V	1.9	2	1.9	V		
		3 V	2.9	3	2.9			
		4.5 V	4.4	4.5	4.4			
	I <sub>OH</sub> = -4 mA	3 V	2.58		2.48			
	I <sub>OH</sub> = -8 mA	4.5 V	3.94		3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V			0.1	0.1	V	
		3 V			0.1	0.1		
		4.5 V			0.1	0.1		
	I <sub>OL</sub> = 4 mA	3 V			0.36	0.44		
	I <sub>OL</sub> = 8 mA	4.5 V			0.36	0.44		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1	±1	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			1	10	μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10	10	pF	



# SN74AHC1G86

## SINGLE 2-INPUT EXCLUSIVE-OR GATE

SCLS323M – MARCH 1996 – REVISED JUNE 2005

switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
$t_{PLH}$	A or B	Y	$C_L = 15\text{ pF}$	7	11	1	13	ns	
$t_{PHL}$				7	11	1	13		
$t_{PLH}$	A or B	Y	$C_L = 50\text{ pF}$	9.5	14.5	1	16.5	ns	
$t_{PHL}$				9.5	14.5	1	16.5		

switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

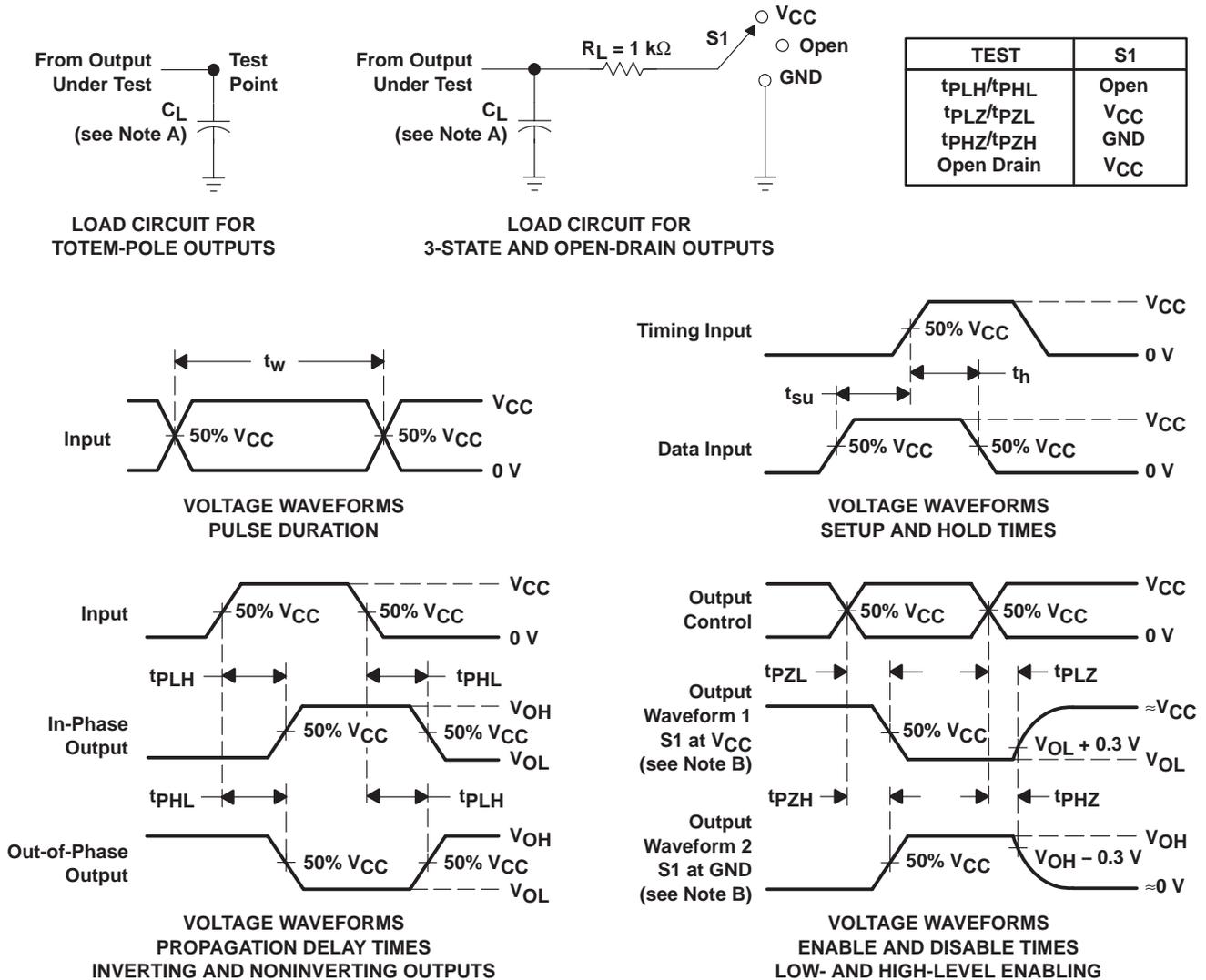
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
$t_{PLH}$	A or B	Y	$C_L = 15\text{ pF}$	4.8	6.8	1	8	ns	
$t_{PHL}$				4.8	6.8	1	8		
$t_{PLH}$	A or B	Y	$C_L = 50\text{ pF}$	6.3	8.8	1	10	ns	
$t_{PHL}$				6.3	8.8	1	10		

operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load, $f = 1\text{ MHz}$	18	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 3 ns, t<sub>f</sub> ≤ 3 ns.  
 D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AHC1G86DBVG4	ACTIVE	SOT-23	DBV	5		TBD	Call TI	Call TI
SN74AHC1G86DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DRLR	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G86DRLRG4	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

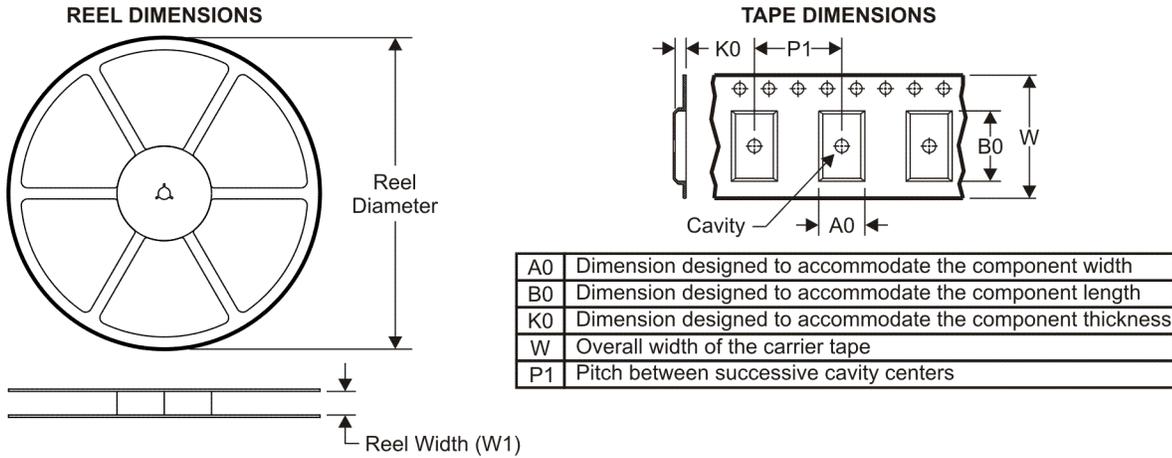
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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

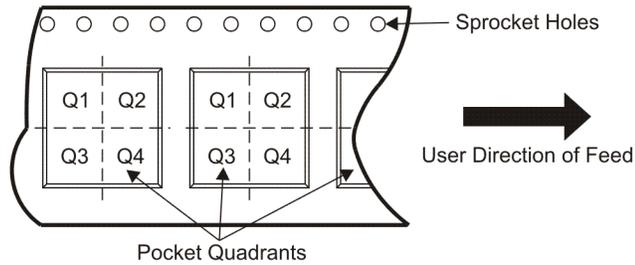
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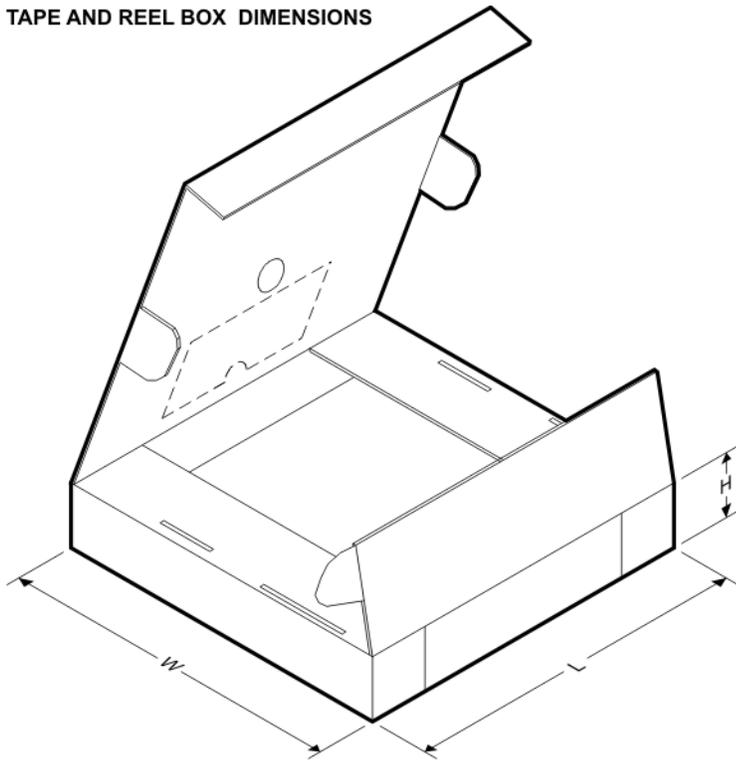
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC1G86DBVR	SOT-23	DBV	5	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G86DBVT	SOT-23	DBV	5	250	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G86DCKR	SC70	DCK	5	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHC1G86DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHC1G86DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHC1G86DCKT	SC70	DCK	5	250	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AHC1G86DRLR	SOT	DRL	5	4000	180.0	9.2	1.78	1.78	0.69	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**

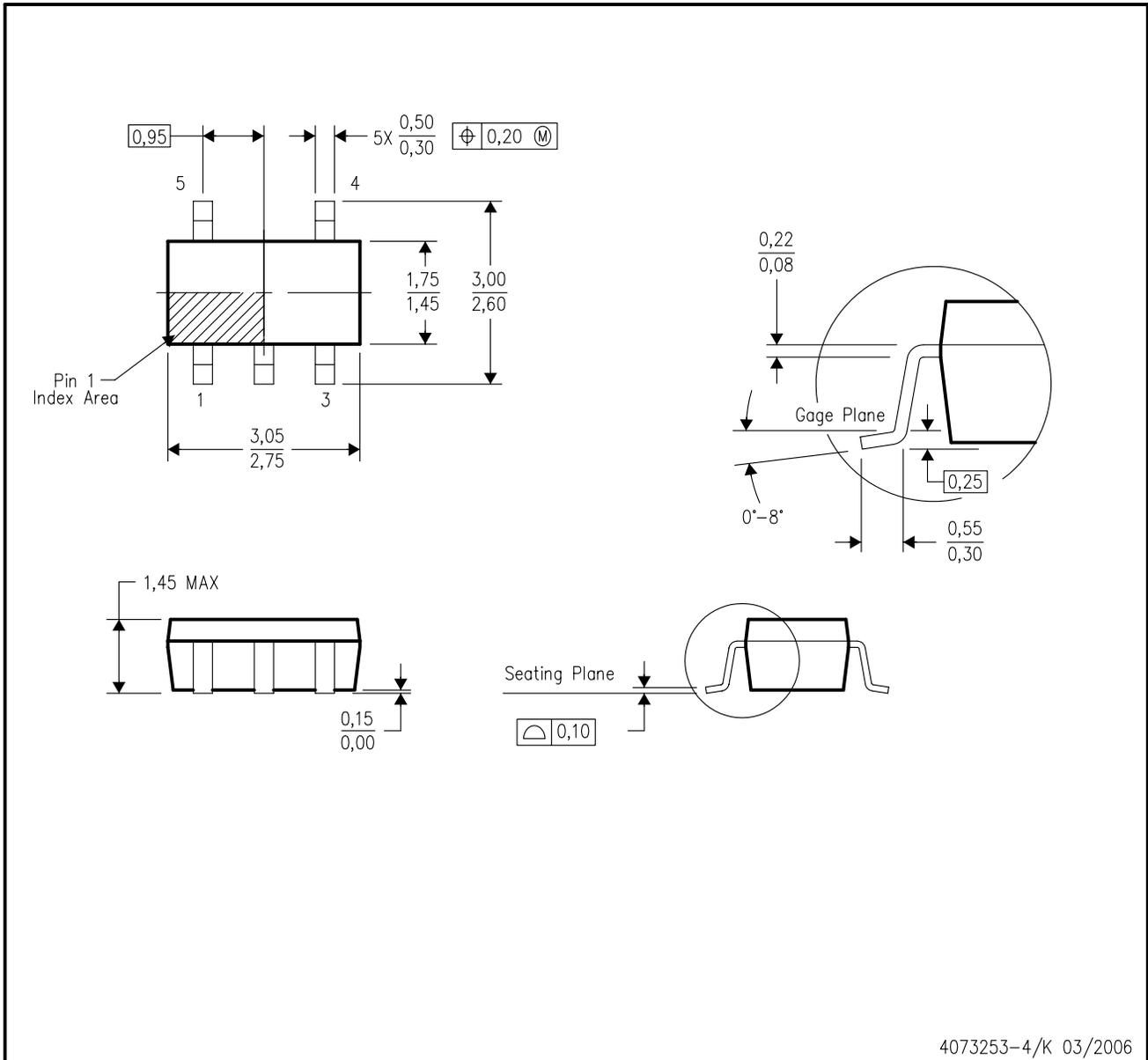


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC1G86DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74AHC1G86DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74AHC1G86DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
SN74AHC1G86DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHC1G86DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74AHC1G86DCKT	SC70	DCK	5	250	202.0	201.0	28.0
SN74AHC1G86DRLR	SOT	DRL	5	4000	202.0	201.0	28.0

DBV (R-PDSO-G5)

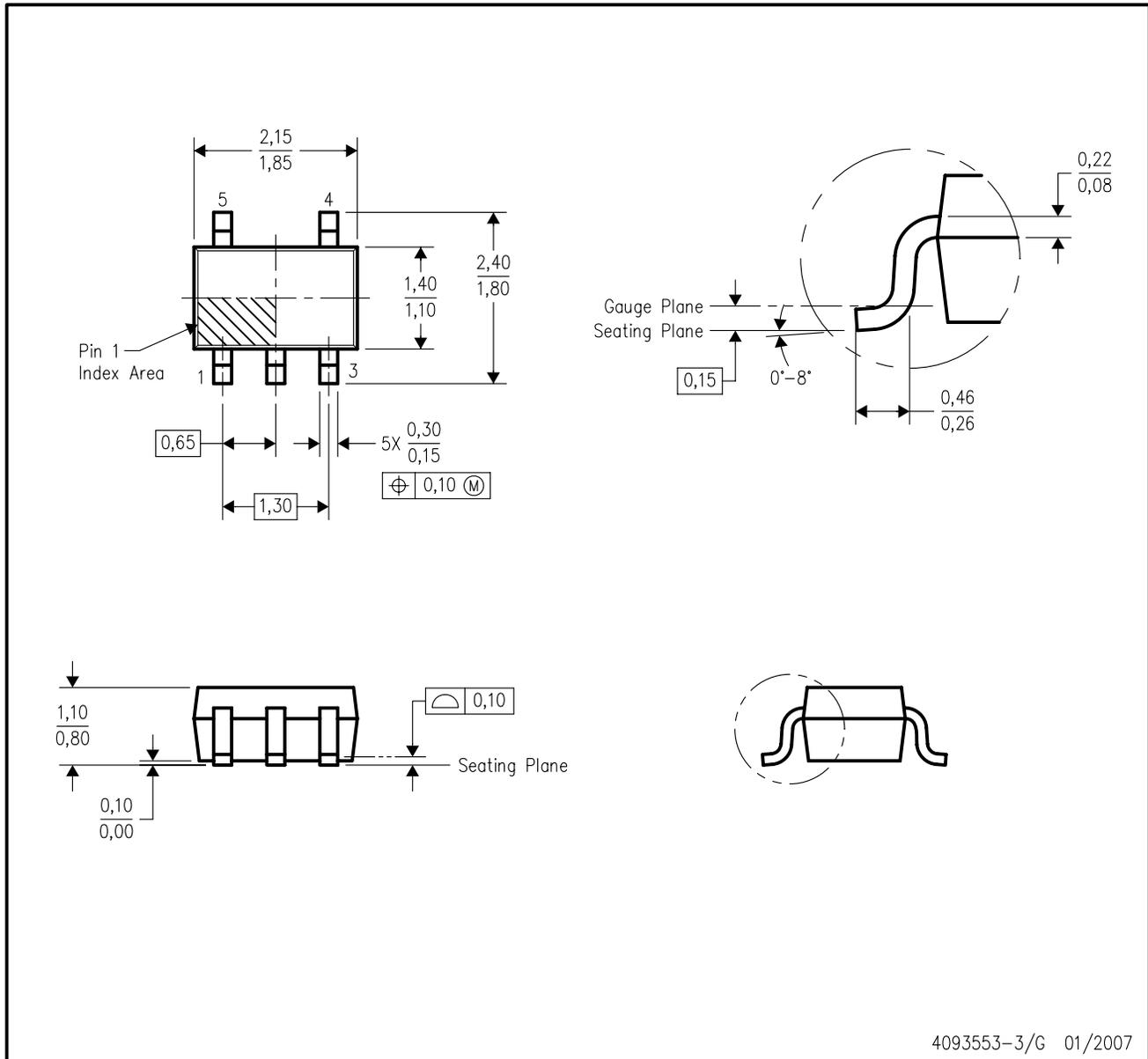
PLASTIC SMALL-OUTLINE PACKAGE



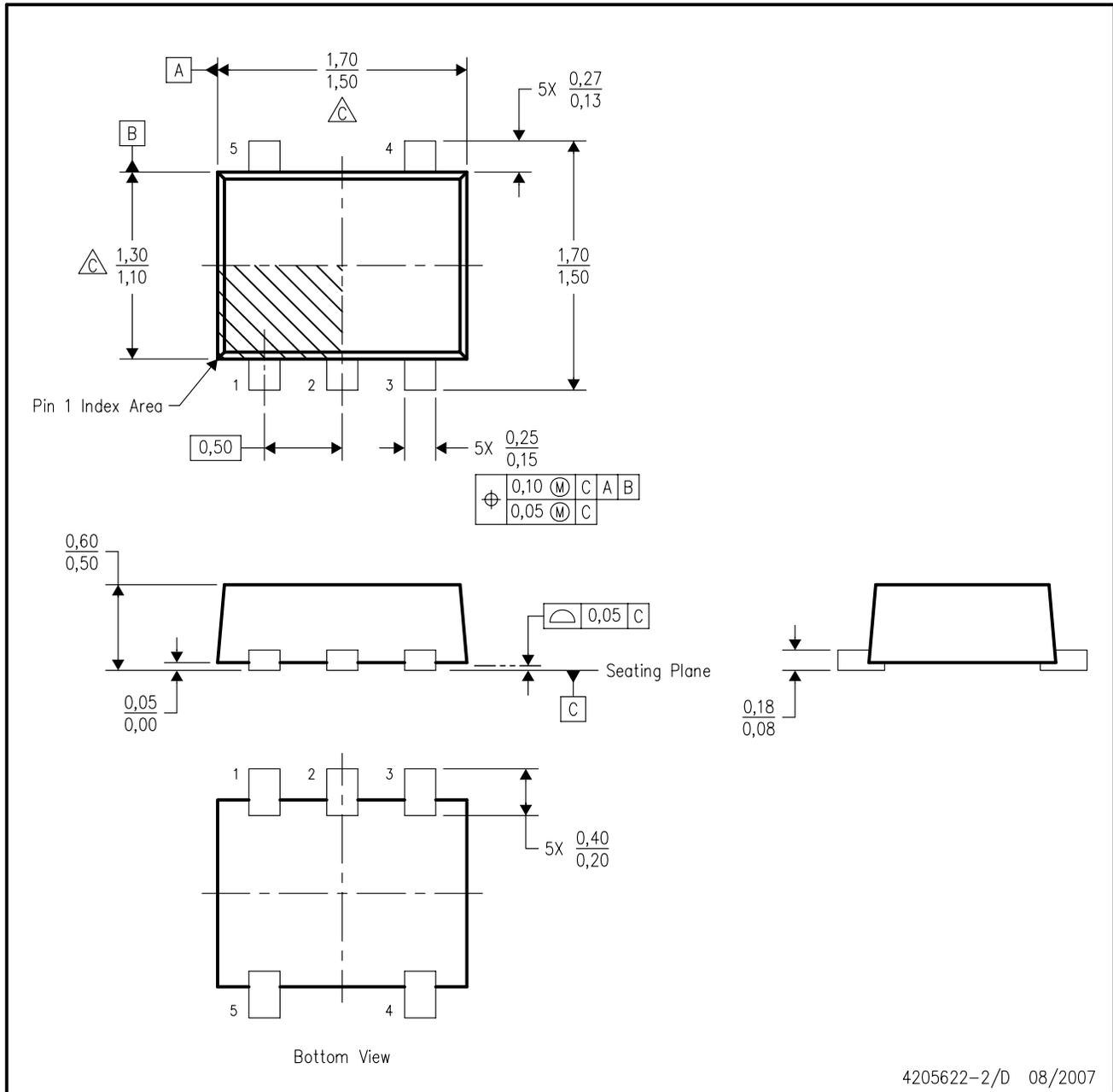
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.

DCK (R-PDSO-G5)

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- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
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  - D. Falls within JEDEC MO-203 variation AA.



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
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  - D. JEDEC package registration is pending.

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